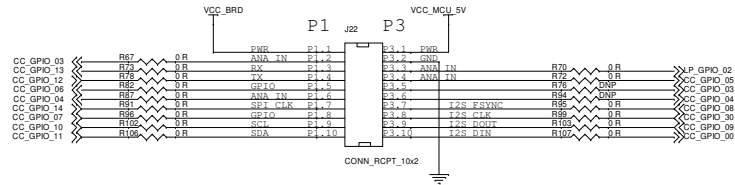


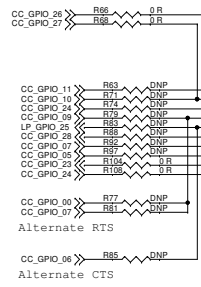
ONLY ONE FLASH USED ON BOARD

		Texas Instruments 66/3 Bagmane Tech Park CV Raman Nagar Bangalore		
		Title: CC3200-LAUNCHXL		
Designer: TI	Approval: TI	Date:	Date:	Rev: 4.1C
Drawn By: TI	Layout: TI	Date:	Date: Wednesday, April 22, 2015	Project No <Project Number>:
Scale:	Date:	Date:	Date:	Sheet 1 of 5

BOOSTER PACK INTERFACE

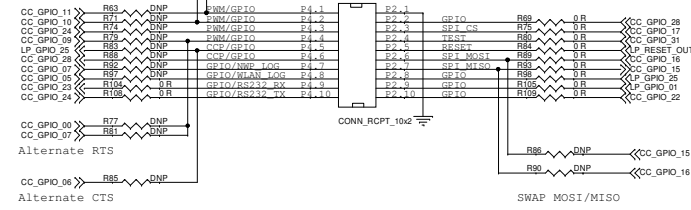


For Antenna diversity



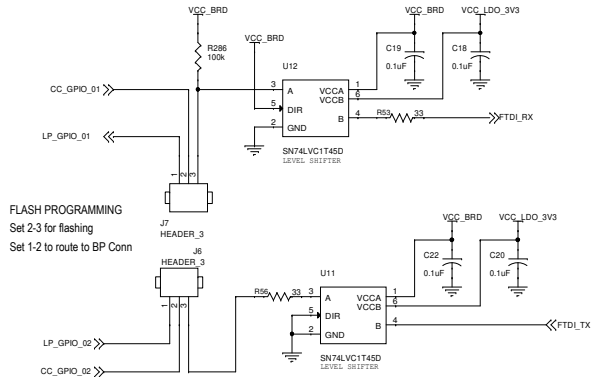
P4

P2



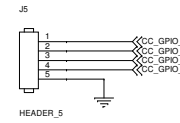
SWAP MOSI/MISO

UART MUXING



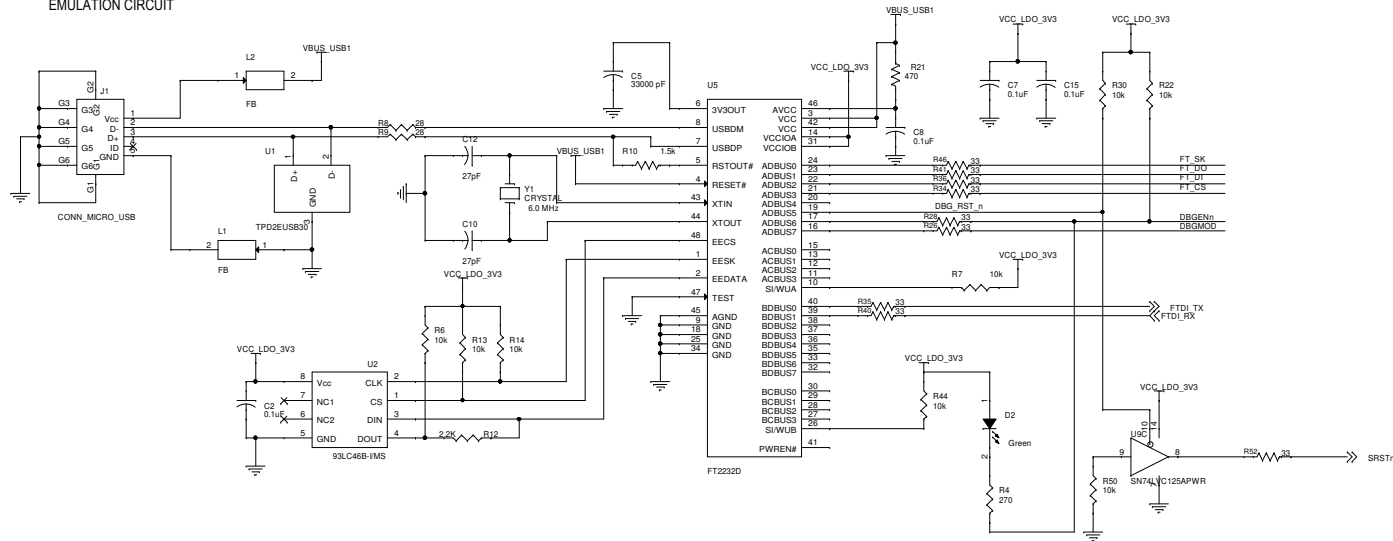
TEST POINTS

OBSERVE NWP & MAC LOG

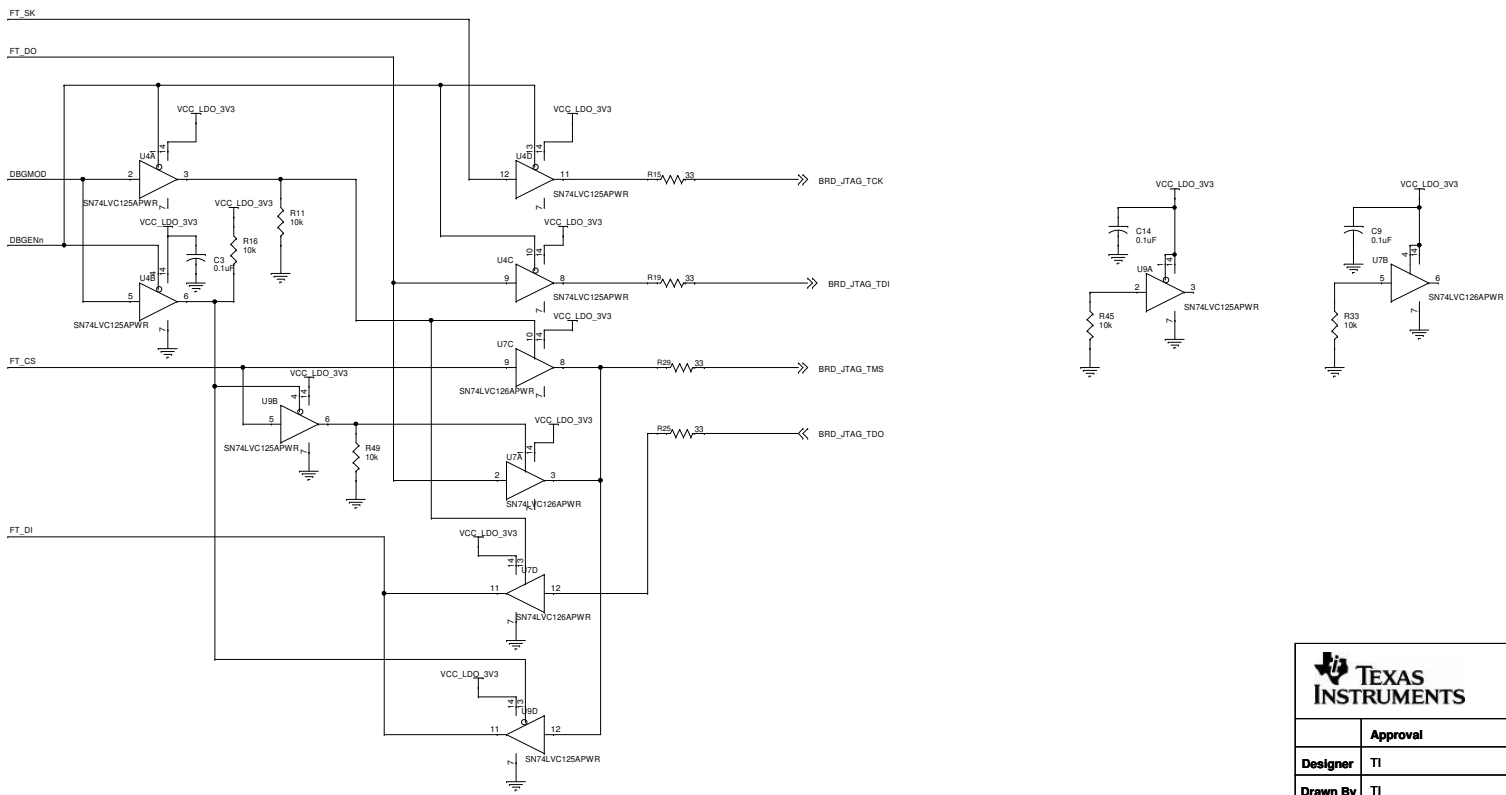


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		Title CC3200-LAUNCHXL			
Approval	TI	Date		Size A2	Project No <Project Number>
Designer	TI	Date		Scale	Rev 4.1
Drawn By	TI	Date		Date	Wednesday, April 22, 2015
Layout	TI	Date		Sheet	2 of 5

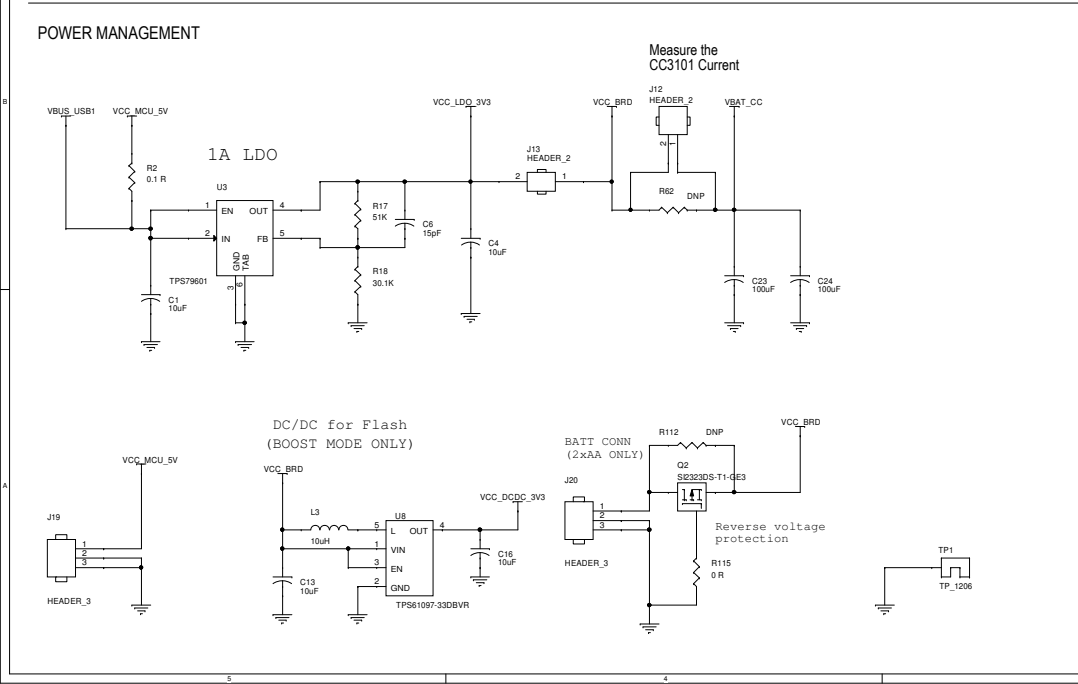
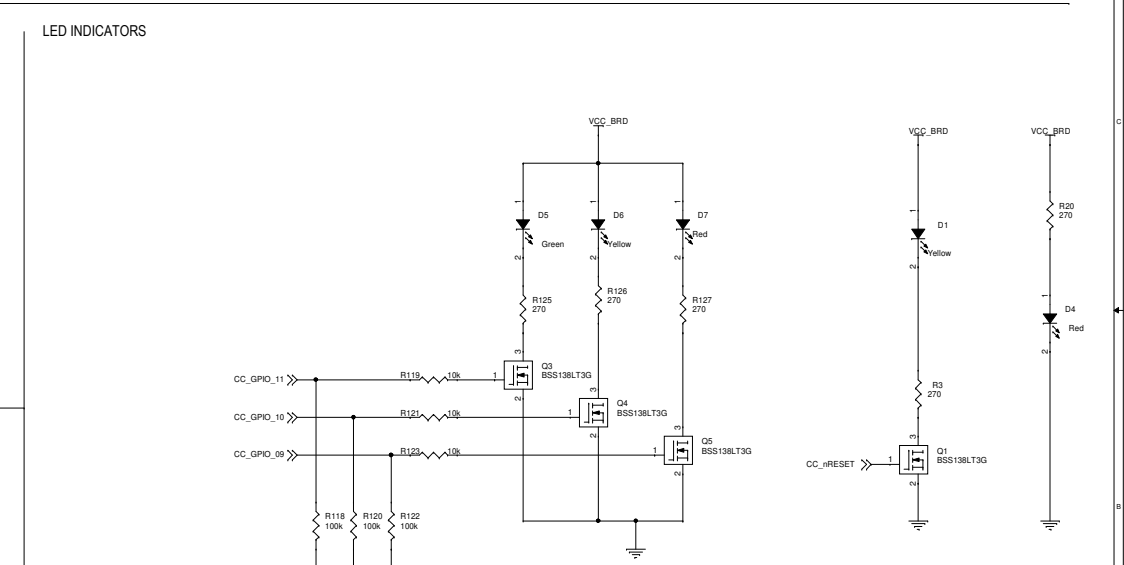
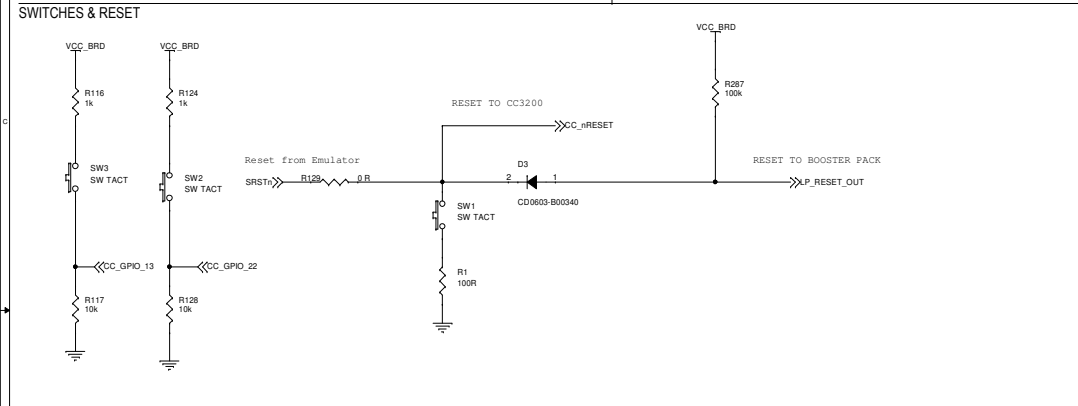
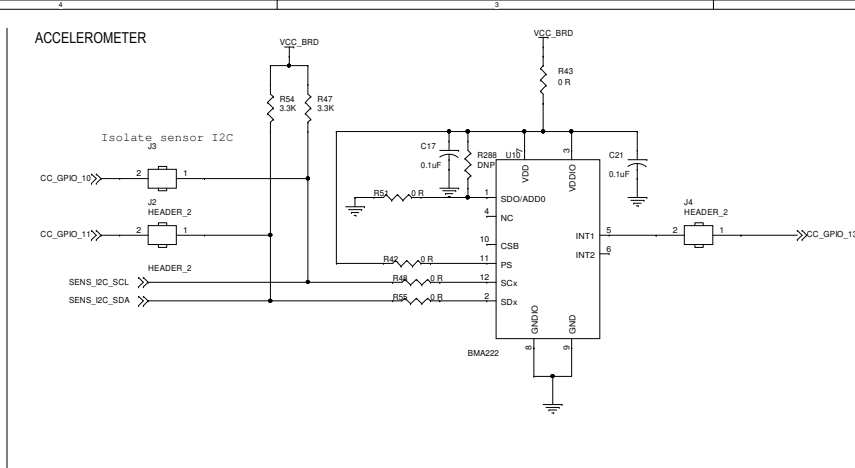
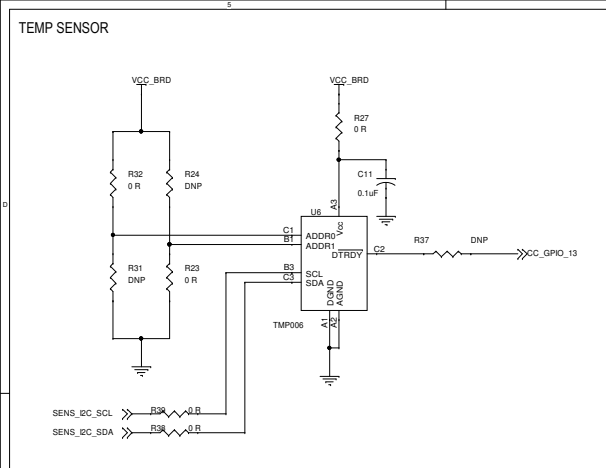
EMULATION CIRCUIT



JTAG/SWD SWITCH



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		Approval Date	Date Title CC3200-LAUNCHXL		
Designer TI	Date	Size A2	Project No <Project Number>	Rev 4.1	
Layout TI	Date	Scale	Date Wednesday, April 22, 2015	Sheet 3 of 5	



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		Title: CC3200-LAUNCHXL		
Approval	T1	Date	Date	
Designer	T1	Date	Size A2	Project No <Project Number>
Drawn By	T1	Date	Scale	Rev 4.1
Layout	T1	Date	Date Wednesday, April 22, 2015	Sheet 4 of 5

Board Revision control naming convention
 X.Y-Z (X= schematic ver, Y = layout version (include silk changes), Z = BOM variant)

Revision history

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Changes in Rev 4.0-A

1. Add pull-ups and pull-down resistors for the serial flash
2. Move the nRESET pull from VCC_BRD to VBAT_CC
3. Add pull-up on UART_TX going to the FTDI to prevent false start bits.
4. Add pull-up resistor for Acccelerometer address to avoid conflict with Audio Booster pack
5. Add 100K pull-up on RESET_OUT net for any BP without RESET pulls.
6. Change R61 to 2.7K, R57-> 270 Ohms

Rev 4.1-B

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1. Changed the s-flash from Micron to Winbond

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			Approval TI		
Designer TI			Title CC3200LAUNCHXL		
Drawn By TI			Size A3	Project No	
Layout TI			Scale	Date Wednesday, April 22, 2015	Rev 4.1 C Sheet 5 of 5

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